L Number	Hits	Search Text	DB	Time stamp
1	1	("5243755").PN.	USPAT	2004/02/16 18:56
-	2242	156/$.ccls. and (control$5) and (stretch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 20:21
-	0	156/$.ccls. and ((correct or correcting or correction) near2 (value or figure or amount)) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	350	(156/358).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	348	(156/351).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	415	(156/359).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	206	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	612	(156/378).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	166	(156/379).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	80	(100/46).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	190	(100/47).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	288	(100/48).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:53
-	227	(100/50).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54

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-	67	(100/51).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	280	(438/7).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	837	(438/16).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	142	156/$.ccls. and (control$5) and (stretch) and (semiconductor or IC or wafer or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 21:37
-	30	156/$.ccls. and (control$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (semiconductor or IC or wafer or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	38	156/$.ccls. and (control$5) and (stretch) and (pcb or (circuit near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 21:38
-	4	156/$.ccls. and (control$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	75	156/$.ccls. and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 18:54
-	1164	(156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 19:01
-	18	156/$.ccls. and (control$5) and (flexure) and (pcb or (circuit near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 21:38
-	69	156/$.ccls. and (control$5) and (flexure) and (semiconductor or IC or wafer or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/15 21:38
-	6854595	JP 11-54877	JPO	2004/02/16 16:12
-	0	11-54877	JPO	2004/02/16 16:12
-	0	11-054877	JPO	2004/02/16 16:12
-	0	h11-054877	JPO	2004/02/16 16:12
-	0	"054877"	JPO	2004/02/16 16:12
-	1	"11054877"	JPO	2004/02/16 17:13
-	3	(("5858806") or ("5243735") or ("6458236")).PN.	USPAT	2004/02/16 18:56

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